



TSMC Reports First Quarter EPS of NT\$1.29

Hsinchu, Taiwan, R.O.C., April 26, 2012 -- TSMC today announced consolidated revenue of NT\$105.51 billion, net income of NT\$33.47 billion, and diluted earnings per share of NT\$1.29 (US\$0.22 per ADR unit) for the first quarter ended March 31, 2012.

Year-over-year, first quarter revenue increased 0.1% while both net income and diluted EPS decreased 7.7%. Compared to fourth quarter of 2011, first quarter of 2012 results represent a 0.8% increase in revenue, and a 6% increase in both net income and diluted EPS. All figures were prepared in accordance with R.O.C. GAAP on a consolidated basis.

In US dollars, first quarter revenue increased 2.7% from the previous quarter and decreased 1.3% year-over-year.

Gross margin for the quarter was 47.7%, operating margin was 33.6%, and net margin was 31.7%.

28-nanometer process technology accounted for 5% of total wafer revenues, 40-nanometer was 32%, and 65-nanometer accounted for 26%. These advanced technologies accounted for 63% of total wafer revenues.

“Due to the fast growth of mobile computing devices, our customers’ replenishing inventories, and TSMC’s leadership in technology and capacity, we have experienced strong orders in the last few months,” said Lora Ho, SVP and Chief Financial Officer of TSMC. “Based on our current business outlook and exchange rate assumption of 1 US dollar to 29.58 NT dollars, management expects overall performance for second quarter 2012 to be as follows”:

- Revenue is expected to be between NT\$126 billion and NT\$128 billion;
- Gross profit margin is expected to be between 47% and 49%;
- Operating profit margin is expected to be between 34.5% and 36.5%.

Due to stronger demand for TSMC’s 28-nanometer technology and the pull-in of a 20-nanometer R&D process line, our estimate for 2012 capital expenditure is raised and is in the US\$8-8.5 billion range.

Conference Call & Webcast Notice:

TSMC’s quarterly review conference call will be held at 8 a.m. Eastern Time (8 p.m. Taiwan Time) on Thursday April 26, 2012. The conference call will also be webcast live on the Internet. Investors wishing to access the live webcast should visit TSMC’s web site at <http://www.tsmc.com> at least 15 minutes prior to the broadcast. Instructions will be provided on the web site to facilitate the download and installation of necessary audio applications. Investors without Internet access may listen to the conference call, in listen-only mode, by dialing **1-718-354-1231** in the U.S., **852-2475-0994** in Hong Kong, and **44-203-059-8139** in the U.K. (Password: TSMC). An archived version of the webcast will be available on TSMC’s web site for six months following the Company’s quarterly review conference call and webcast.

Profile

TSMC is the world's largest dedicated semiconductor foundry, providing the industry's leading process technology and the foundry's largest portfolio of process-proven libraries, IPs, design tools and reference flows. The Company's managed capacity in 2011 was about 13.2 million (8-inch equivalent) wafers, including capacity from two advanced 12-inch GIGAFABs™, four eight-inch fabs, one six-inch fab, as well as TSMC's wholly owned subsidiaries, WaferTech and TSMC China, and its joint venture fab, SSMC. TSMC is the first foundry to provide 28nm production capabilities. Its corporate headquarters are in Hsinchu, Taiwan. For more information about TSMC please visit <http://www.tsmc.com>.

(Management Report and Tables Follow)

CONTACT

Elizabeth Sun

Corporate Communication Division

TSMC

invest@tsmc.com

886-3-568-2085

Safe Harbor Notice:

The statements included in this press release that are not historical in nature are "forward-looking statements" within the meaning of the "safe harbor" provisions of the Private Securities Litigation Reform Act of 1995. TSMC cautions readers that forward-looking statements are subject to significant risks and uncertainties and are based on TSMC's current expectations. Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including, among others, risks associated with cyclical and market conditions in the semiconductor industry; demand and supply for TSMC's foundry manufacturing capacity in particular and for foundry manufacturing capacity in general; intense competition; the failure of one or more significant customers to continue to place the same level of orders with us; TSMC's ability to remain a technological leader in the semiconductor industry; TSMC's ability to manage its capacity; TSMC's ability to obtain, preserve and defend its intellectual property rights; natural disasters and other unexpected events which may disrupt production; and exchange rate fluctuations. Additional information as to these and other risk factors that may cause TSMC's actual results to differ materially from TSMC's forward-looking statements may be found in TSMC's Annual Report on Form 20-F, filed with the United States Securities and Exchange Commission (the "SEC") on April 13, 2012, and such other documents as TSMC may file with, or submit to, the SEC from time to time. Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.